ABSTRACT OF THE DISCLOSURE

A heat-peelable pressure-sensitive adhesive sheet which, even when used for temporarily fixing electronic parts having poor resistance to static electricity, such as magnetic heads, is effective in preventing the yield of such electronic parts from being reduced by electrostatic breakage, while ensuring its functions of adhesiveness before heating and peelability after heating. The heat-peelable pressure-sensitive adhesive sheet comprises a substrate and formed on at least one side thereof a heat-expandable pressure-sensitive adhesive layer containing heat-expandable microspheres, wherein the heat-expandable pressure-sensitive adhesive layer has a surface resistivity of 10^{12} Ω/□ or lower. In this heat-peelable pressure-sensitive adhesive sheet, the heat-expandable pressure-sensitive adhesive layer before heating may have a center line average surface roughness of 2 μm or less and a maximum surface roughness of 5 μm or less. The adhesive sheet may have a rubber-like organic elastic layer interposed between the substrate and the heat-expandable pressure-sensitive adhesive layer.

This Sheet Has Been Replaced

